



#### SM6S20A THRU SM6S36A TRANSIENT VOLTAGE SUPPRESSOR



#### **Features**

- Junction passivation optimized design passivated anisotropic rectifier technology
- T<sub>J</sub> = 175<sup>o</sup>C capability suitable for high reliability and automotive requirement.
- Available in uni-directional polarity only
- Low leakage current
- Low forward voltage drop
- · High surge capability
- AEC-Q101 qualified.

#### **Circuit Diagram**



#### **Mechanical Data**

- Case: DO-218AB
- Molding compound meets UL 94V-0 flammability rating
- Base P/NHE3-RoHS-compliant, AEC-Q101 qualified
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

#### Maximum Ratings and Thermal Characteristics@T<sub>A</sub>=25°C unless otherwise specified

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 10/1000 µs waveform	P <sub>PPM</sub>	4600	W
Peak pulse power dissipation on 10/10000 µs waveform	ГРРМ	3600	W
Power dissipation on infinite heat sink at T <sub>C</sub> = 25°C	P <sub>D</sub>	6.0	W
Peak forward surge current 8.3 ms single half sine-wave	I <sub>FSM</sub>	600	А
Typical thermal resistance, junction to case	Rejc	0.95	°C/W
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 to 175	°C



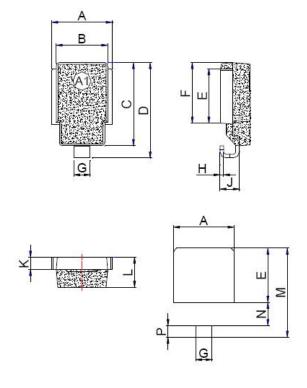




#### Electrical Characteristics@TA=25° C unless otherwise specified

DEVICE TYPE	REVERSE STAND-OFF VOLTAGE V <sub>RWM</sub> (V)	VOL V <sub>B</sub>	KDOWN TAGE R (V)	TEST CURRENT I <sub>T</sub>	CLAMPING VOLTAGE V <sub>C</sub> @I <sub>PP</sub>	PEAK PULSE CURRENT AT 10/1000µs WAVEFORM IPP		E LEAKAGE RRENT I <sub>R</sub>
		MIN.	MAX.	MA	V	Α	μA@25°C	μA@175°C
SM6S20A	20	22.2	24.5	5	32.4	142	5	150
SM6S22A	22	24.4	26.9	5	35.5	130	5	150
SM6S24A	24	26.7	29.5	5	38.9	118	5	150
SM6S26A	26	28.9	31.9	5	42.1	109	5	150
SM6S28A	28	31.1	34.4	5	45.4	101	5	150
SM6S30A	30	33.3	36.8	5	48.4	95	5	150
SM6S33A	33	36.7	40.6	5	53.3	86	5	150
SM6S36A	36	40.0	44.2	5	58.1	79	5	150

# **Mechanical Dimensions DO-218AB(Inches/Millimeters)**



Cumbal	Millir	neters	Inches		
Symbol	Min.	Max.	Min.	Max.	
А	9.5	10.5	0.374	0.413	
В	8.3	8.7	0.327	0.342	
С	13.3	13.7	0.524	0.539	
D	15.0	16.0	0.592	0.628	
Е	8.5	9.1	0.335	0.358	
F	9.5	10.1	0.374	0.398	
G	2.4	3.0	0.094	0.118	
Н	0.5	0.7	0.020	0.028	
J	2.7	3.7	0.106	0.146	
K	1.9	2.1	0.075	0.083	
L	4.7	5.1	0.185	0.201	
М	14.2	14.8	0.559	0.583	
N	3.5	4.1	0.138	0.161	
Р	1.6	2.2	0.063	0.087	

<sup>•</sup> China - Germany - Korea - Singapore - United States •

<sup>•</sup> http://www.smc-diodes.com - sales@ smc-diodes.com •





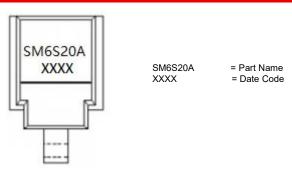


### **Ordering Information**

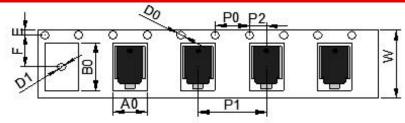
Device	Package	Shipping
SM6S20A THRU	DO-218AB	750pcs / reel
SM6S36A		•

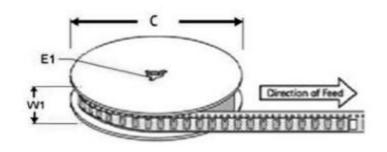
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

# **Marking Diagram**



### **Carrier Tape Specification DO-218AB**





20.20	Dimensions			
Ref.	Millimeters	Inches		
A0	10.80 ± 0.3	0.425± 0.012		
В0	16.13 ± 0.3	0.635 ± 0.012		
С	330.0 ± 0.3	13.0 ± 0.012		
D0	1.55 ± 0.2	0.061 ± 0.008		
D1	1.55 ± 0.2	0.061± 0.008		
E	1.75 ± 0.2	0.069 ± 0.008		
E1	13.30 ± 0.2	0.524 ± 0.008		
F	11.50 ± 0.2	0.453 ± 0.008		
P0	4.00 ± 0.2	0.157 ± 0.008		
P1	16.00 ± 0.2	0.630 ± 0.008		
P2	2.00 ± 0.2	0.079 ± 0.008		
W	24.00 ± 0.2	0.945 ± 0.008		
W 1	25.85 ± 0.2	1.018 ± 0.008		





### **Ratings and Characteristics Curves**

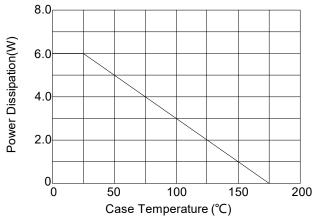


FIG.1: Power Derating Curve

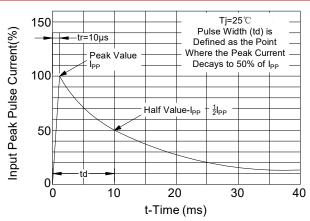
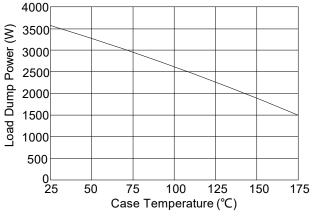


FIG.2: Pulse Waveform



**FIG.3:** Load Dump Power Characteristics (10ms Exponential Waveform)

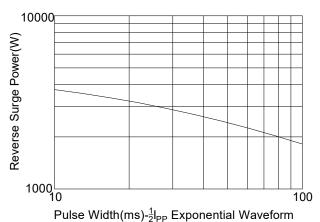


FIG.4: Reverse Power Capability

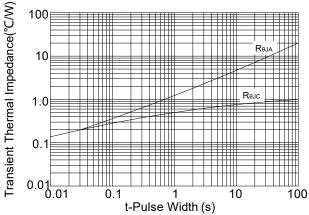


FIG.5: Typical Transient Thermal Impedance

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